台積電2026校園徵才開跑 正職與實習同步招募

即時

【林品瑜淡水校園報導】想進入全球半導體龍頭產業實習或就職嗎？台灣積體電路製造公司（TSMC）近日公布2026年徵才計畫，於3月期間在全臺多所大專校院舉辦實體說明會，並安排多場線上說明會，其中3月23日將針對國際學生進行全英文線上徵才及實習說明會，介紹職缺內容與申請方式，歡迎有意投入半導體產業的學生踴躍報名。（網址：https://reurl.cc/N2ZYK5 ）。

此次校園徵才採「正職招募」與「DNA積因實習計畫」雙軌進行。正職招募對象為2026年應屆畢業生或可於年底前到職者，職缺涵蓋研發、營運、策略業務、資訊技術、人力資源及財務會計等多元領域，申請截止至4月30日，甄選將於6月30日前完成；「DNA積因實習計畫」則針對大三以上全職學生開放，申請截止至5月8日，實習期間為7月6日至8月28日，若學生就讀學校或戶籍地不在實習所在地縣市，亦可自費申請公司宿舍。更多詳情可至台積電官方網站查詢。

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2026台積電
校園徵才活動

活動介紹

就業博覽會（請參照各校博覽會時程）
與台積學長姐、HR聊聊，瞭解台積職務及工作型態、職涯發展。

【實體】徵才說明會
03/16 (一) 屏科大 | 15:30-16:30
03/18 (三) 虎科 | 12:20-13:20
03/21 (六) 中興 | 11:30-12:15 或 13:15-14:00
03/24 (二) 高師大 | 12:20-13:20
03/25 (三) 雲科 | 11:30-12:30
03/26 (四) 臺師大 | 18:30-19:30

【線上】徵才說明會 12:15-13:15
03/13 (五) 中文 | 實習專場
03/17 (二) 中文 | 徵才專場
03/24 (二) 中文 | 非理工專場
03/26 (四) 中文 | 徵才專場
03/23 (一) 英文 | 徵才及實習專場

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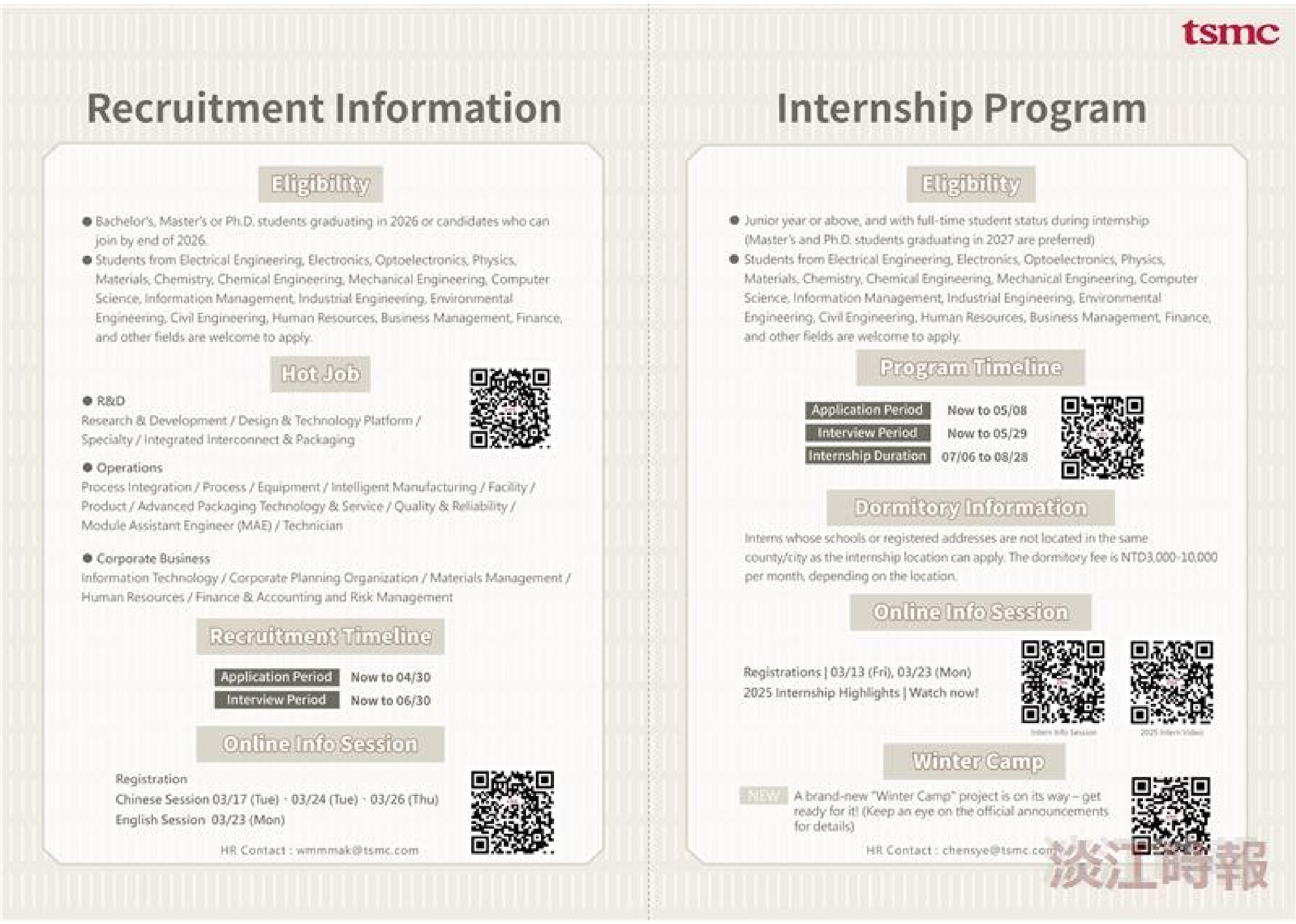
2026 TSMC
Campus Recruitment

Event Details

Job Fair - Meet with us!
Whether you are interested in cutting-edge R&D, Operations, Corporate Business positions, this is your chance to gain exclusive insights into a world's leading foundry. Don't miss this chance to jumpstart your professional journey with TSMC - we look forward to meeting you!

On-campus Info Session
03/16 (Mon) NPUST | 15:30-16:30
03/18 (Wed) NFU | 12:20-13:20
03/21 (Sat) NCHU | 11:30-12:15 or 13:15-14:00
03/24 (Tue) NKNU | 12:20-13:20
03/25 (Wed) YunTech | 11:30-12:30
03/26 (Thu) NTNU | 18:30-19:30

Online Info Session 12:15-13:15
03/13 (Fri) Chinese | DNA Internship
03/17 (Tue) Chinese | Recruitment
03/24 (Tue) Chinese | Non-STEM
03/26 (Thu) Chinese | Recruitment
03/23 (Mon) English | Recruitment & DNA Internship



Recruitment Information

Eligibility

- Bachelor's, Master's or Ph.D. students graduating in 2026 or candidates who can join by end of 2026.
- Students from Electrical Engineering, Electronics, Optoelectronics, Physics, Materials, Chemistry, Chemical Engineering, Mechanical Engineering, Computer Science, Information Management, Industrial Engineering, Environmental Engineering, Civil Engineering, Human Resources, Business Management, Finance, and other fields are welcome to apply.

Hot Job

- **R&D**

Research & Development / Design & Technology Platform / Specialty / Integrated Interconnect & Packaging

- **Operations**

Process Integration / Process / Equipment / Intelligent Manufacturing / Facility / Product / Advanced Packaging Technology & Service / Quality & Reliability / Module Assistant Engineer (MAE) / Technician

- **Corporate Business**

Information Technology / Corporate Planning Organization / Materials Management / Human Resources / Finance & Accounting and Risk Management

Recruitment Timeline

Application Period	Now to 04/30
Interview Period	Now to 06/30

Online Info Session

Registration
Chinese Session 03/17 (Tue)、03/24 (Tue)、03/26 (Thu)
English Session 03/23 (Mon)

HR Contact : wmmmak@tsmc.com

Internship Program

Eligibility

- Junior year or above, and with full-time student status during internship (Master's and Ph.D. students graduating in 2027 are preferred)
- Students from Electrical Engineering, Electronics, Optoelectronics, Physics, Materials, Chemistry, Chemical Engineering, Mechanical Engineering, Computer Science, Information Management, Industrial Engineering, Environmental Engineering, Civil Engineering, Human Resources, Business Management, Finance, and other fields are welcome to apply.

Program Timeline

Application Period	Now to 05/08
Interview Period	Now to 05/29
Internship Duration	07/06 to 08/28

Dormitory Information

Interns whose schools or registered addresses are not located in the same county/city as the internship location can apply. The dormitory fee is NTD3,000-10,000 per month, depending on the location.

Online Info Session

Registrations | 03/13 (Fri), 03/23 (Mon)
2025 Internship Highlights | Watch now!

Intern Info Session
2025 Intern Video

Winter Camp

NEW A brand-new "Winter Camp" project is on its way – get ready for it! (Keep an eye on the official announcements for details)

HR Contact : chensye@tsmc.com